Application Note

AVAILABLE

AN99 • AN115 • AN120 • AN124 • AN133 • AN134 • AN135

Low Noise/Low Power/SPI Bus/256 Taps



X9250

Quad Digitally Controlled Potentiometers (XDCP[™])

FEATURES

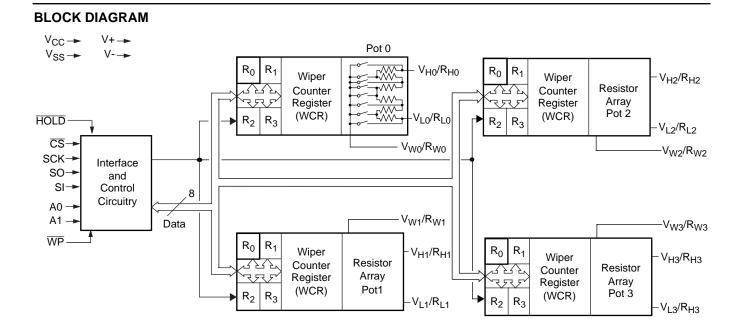
- Four potentiometers in one package
- 256 resistor taps/pot-0.4% resolution
- SPI serial interface
- Wiper resistance, 40 Ω typical @ V_{CC} = 5V
- Four nonvolatile data registers for each pot
- Nonvolatile storage of wiper position
- Standby current < 5µA max (total package)
- Power supplies
 - -V_{CC} = 2.7V to 5.5V
 - —V+ = 2.7V to 5.5V
- —V– = -2.7V to -5.5V
- 100K Ω , 50K Ω total pot resistance
- High reliability
 - —Endurance 100,000 data changes per bit per register
 - -Register data retention 100 years
- 24-lead SOIC, 24-lead TSSOP, 24-lead CSP (Chip Scale Package)
- Dual supply version of X9251

DESCRIPTION

The X9250 integrates 4 digitally controlled potentiometers (XDCP) on a monolithic CMOS integrated circuit.

The digitally controlled potentiometer is implemented using 255 resistive elements in a series array. Between each element are tap points connected to the wiper terminal through switches. The position of the wiper on the array is controlled by the user through the SPI bus interface. Each potentiometer has associated with it a volatile Wiper Counter Register (WCR) and 4 nonvolatile Data Registers (DR0:DR3) that can be directly written to and read by the user. The contents of the WCR controls the position of the wiper on the resistor array though the switches. Power up recalls the contents of DR0 to the WCR.

The XDCP can be used as a three-terminal potentiometer or as a two-terminal variable resistor in a wide variety of applications including control, parameter adjustments, and signal processing.



PIN DESCRIPTIONS

Serial Output (SO)

SO is a serial data output pin. During a read cycle, data is shifted out on this pin. Data is clocked out by the falling edge of the serial clock.

Serial Input

SI is the serial data input pin. All opcodes, byte addresses and data to be written to the pots and pot registers are input on this pin. Data is latched by the rising edge of the serial clock.

Serial Clock (SCK)

The SCK input is used to clock data into and out of the X9250.

Chip Select (CS)

When \overline{CS} is HIGH, the X9250 is deselected and the SO pin is at high impedance, and (unless an internal write cycle is underway) the device will be in the standby state. \overline{CS} LOW enables the X9250, placing it in the active power mode. It should be noted that after a power-up, a HIGH to LOW transition on \overline{CS} is required prior to the start of any operation.

Hold (HOLD)

HOLD is used in conjunction with the \overline{CS} pin to select the device. Once the part is selected and a serial sequence is underway, HOLD may be used to pause the serial communication with the controller without resetting the serial sequence. To pause, HOLD must be brought LOW while SCK is LOW. To resume communication, HOLD is brought HIGH, again while SCK is LOW. If the pause feature is not used, HOLD should be held HIGH at all times.

Device Address (A₀–A₁)

The address inputs are used to set the least significant 2 bits of the 8-bit slave address. A match in the slave address serial data stream must be made with the address input in order to initiate communication with the X9250. A maximum of 4 devices may occupy the SPI serial bus.

Potentiometer Pins

$V_{H}/R_{H} (V_{H0}/R_{H0}-V_{H3}/R_{H3}), V_{L}/R_{L} (V_{L0}/R_{L0}-V_{L3}/R_{L3})$

The R_H and R_L pins are equivalent to the terminal connections on a mechanical potentiometer.

V_W/R_W (V_{W0}/R_{W0}-V_{W3}/R_{W3})

The wiper pins are equivalent to the wiper terminal of a mechanical potentiometer.

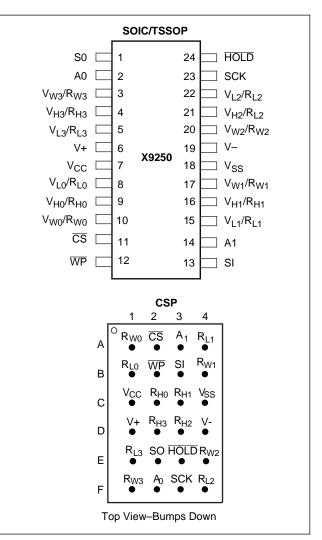
Hardware Write Protect Input (WP)

The $\overline{\text{WP}}$ pin when LOW prevents nonvolatile writes to the Data Registers.

Analog Supplies (V+, V-)

The analog supplies V+, V- are the supply voltages for the XDCP analog section.

PIN CONFIGURATION



PIN NAMES

Symbol	Description
SCK	Serial Clock
SI, SO	Serial Data
A ₀ -A ₁	Device Address
$V_{H0}/R_{H0}-V_{H3}/R_{H3}, V_{L0}/R_{L0}-V_{L3}/R_{L3}$	Potentiometer Pins (terminal equivalent)
V _{W0} /R _{W0} _V _{W3} /R _{W3}	Potentiometer Pins (wiper equivalent)
WP	Hardware Write Protection
V+,V-	Analog Supplies
V _{CC}	System Supply Voltage
V _{SS}	System Ground
NC	No Connection

DEVICE DESCRIPTION

Serial Interface

The X9250 supports the SPI interface hardware conventions. The device is accessed via the SI input with data clocked in on the rising SCK. \overline{CS} must be LOW and the HOLD and \overline{WP} pins must be HIGH during the entire operation.

The SO and SI pins can be connected together, since they have three state outputs. This can help to reduce system pin count.

Array Description

The X9250 is comprised of four resistor arrays. Each array contains 255 discrete resistive segments that are connected in series. The physical ends of each array are equivalent to the fixed terminals of a mechanical potentiometer (V_H/R_H and V_L/R_L inputs).

At both ends of each array and between each resistor segment is a CMOS switch connected to the wiper (V_W/R_W) output. Within each individual array only one switch may be turned on at a time.

These switches are controlled by a Wiper Counter Register (WCR). The 8 bits of the WCR are decoded to select, and enable, one of 256 switches.

Wiper Counter Register (WCR)

The X9250 contains four Wiper Counter Registers, one for each XDCP potentiometer. The WCR is equivalent to a serial-in, parallel-out register/counter with its outputs decoded to select one of 256 switches along its resistor array. The contents of the WCR can be altered in four ways: it may be written directly by the host via the write Wiper Counter Register instruction (serial load); it may be written indirectly by transferring the contents of one of four associated Data Registers via the XFR Data Register or Global XFR Data Register instructions (parallel load); it can be modified one step at a time by the increment/decrement instruction. Finally, it is loaded with the contents of its Data Register zero (DR0) upon power-up.

The Wiper Counter Register is a volatile register; that is, its contents are lost when the X9250 is powereddown. Although the register is automatically loaded with the value in R0 upon power-up, this may be different from the value present at power-down.

Data Registers

Each potentiometer has four 8-bit nonvolatile Data Registers. These can be read or written directly by the host. Data can also be transferred between any of the four Data Registers and the associated Wiper Counter Register. All operations changing data in one of the Data Registers is a nonvolatile operation and will take a maximum of 10ms.

If the application does not require storage of multiple settings for the potentiometer, the Data Registers can be used as regular memory locations for system parameters or user preference data.

Data Register Detail

(MSB)							(LSB)
D7	D6	D5	D4	D3	D2	D1	D0
NV	NV	NV	NV	NV	NV	NV	NV

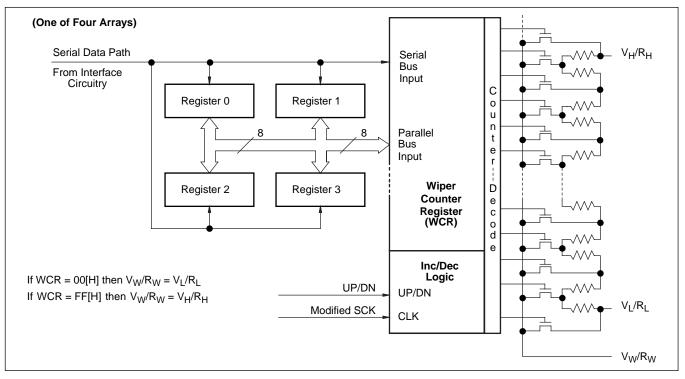


Figure 1. Detailed Potentiometer Block Diagram

Write in Process

The contents of the Data Registers are saved to nonvolatile memory when the \overline{CS} pin goes from LOW to HIGH after a complete write sequence is received by the device. The progress of this internal write operation can be monitored by a write in process bit (WIP). The WIP bit is read with a read status command.

INSTRUCTIONS

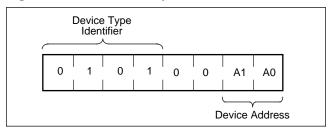
Identification (ID) Byte

The first byte sent to the X9250 from the host, following a \overline{CS} going HIGH to LOW, is called the Identification byte. The most significant four bits of the slave address are a device type identifier, for the X9250 this is fixed as 0101[B] (refer to Figure 2).

The two least significant bits in the ID byte select one of four devices on the bus. The physical device address is defined by the state of the A_0 - A_1 input pins. The X9250 compares the serial data stream with the address input state; a successful compare of both address bits is required for the X9250 to successfully continue the command sequence. The A_0 - A_1 inputs can be actively driven by CMOS input signals or tied to V_{CC} or V_{SS} .

The remaining two bits in the slave byte must be set to 0.

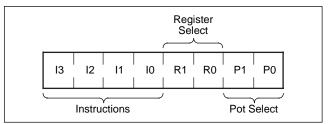
Figure 2. Identification Byte Format



Instruction Byte

The next byte sent to the X9250 contains the instruction and register pointer information. The four most significant bits are the instruction. The next four bits point to one of the four pots and, when applicable, they point to one of four associated registers. The format is shown below in Figure 3.

Figure 3. Instruction Byte Format



The four high order bits of the instruction byte specify the operation. The next two bits (R_1 and R_0) select one of the four registers that is to be acted upon when a register oriented instruction is issued. The last two bits (P1 and P₀) selects which one of the four potentiometers is to be affected by the instruction.

Four of the ten instructions are two bytes in length and end with the transmission of the instruction byte. These instructions are:

- <u>XFR Data Register to Wiper Counter Register</u>—This transfers the contents of one specified Data Register to the associated Wiper Counter Register.
- <u>XFR Wiper Counter Register to Data Register</u>—This transfers the contents of the specified Wiper Counter Register to the specified associated Data Register.
- <u>Global XFR Data Register to Wiper Counter Register</u> This transfers the contents of all specified Data Registers to the associated Wiper Counter Registers.
- <u>Global XFR Wiper Counter Register to Data Register</u> This transfers the contents of all Wiper Counter Registers to the specified associated Data Registers.

The basic sequence of the two byte instructions is illustrated in Figure 4. These two-byte instructions exchange data between the WCR and one of the Data Registers. A transfer from a Data Register to a WCR is essentially a write to a static RAM, with the static RAM controlling the wiper position. The response of the wiper to this action will be delayed by t_{WRL} . A transfer from the WCR (current wiper position), to a Data Register is a write to nonvolatile memory and takes a minimum of t_{WR} to complete. The transfer can occur between one of the four potentiometers and one of its associated registers; or it may occur globally, where the transfer occurs between all potentiometers and one associated register.

Five instructions require a three-byte sequence to complete. These instructions transfer data between the host and the X9250; either between the host and one of the data registers or directly between the host and the Wiper Counter Register. These instructions are:

- <u>Read Wiper Counter Register</u>—read the current wiper position of the selected pot,
- <u>Write Wiper Counter Register</u>—change current wiper position of the selected pot,
- <u>Read Data Register</u>—read the contents of the selected data register;
- <u>Write Data Register</u>—write a new value to the selected data register.
- <u>Read Status</u>—This command returns the contents of the WIP bit which indicates if the internal write cycle is in progress.

The sequence of these operations is shown in Figure 5 and Figure 6.

The final command is Increment/Decrement. It is different from the other commands, because it's length is indeterminate. Once the command is issued, the master can clock the selected wiper up and/or down in one resistor segment steps; thereby, providing a fine tuning capability to the host. For each SCK clock pulse (t_{HIGH}) while SI is HIGH, the selected wiper will move one resistor segment towards the V_H/R_H terminal. Similarly, for each SCK clock pulse while SI is LOW, the selected wiper will move one resistor segment towards the V_L/R_L terminal. A detailed illustration of the sequence and timing for this operation are shown in Figure 7 and Figure 8.

X9250

Figure 4. Two-Byte Instruction Sequence

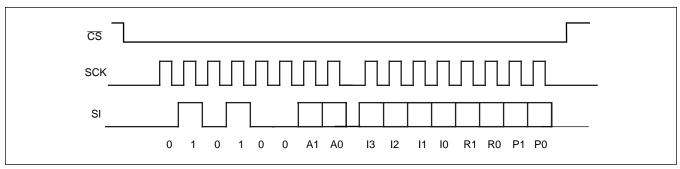


Figure 5. Three-Byte Instruction Sequence (Write)

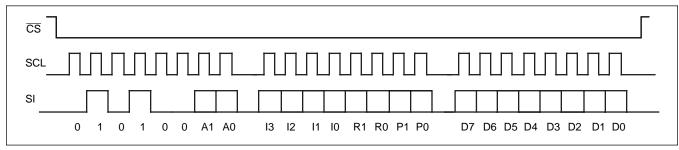


Figure 6. Three-Byte Instruction Sequence (Read)

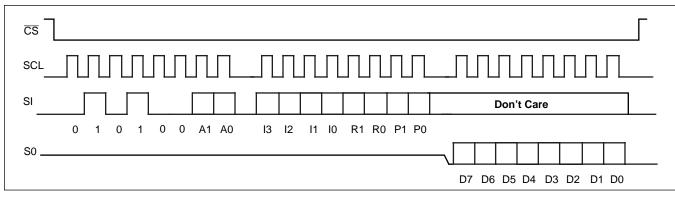


Figure 7. Increment/Decrement Instruction Sequence

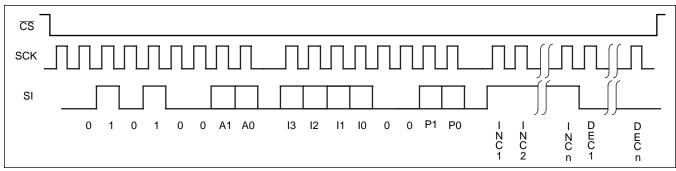


Figure 8. Increment/Decrement Timing Limits

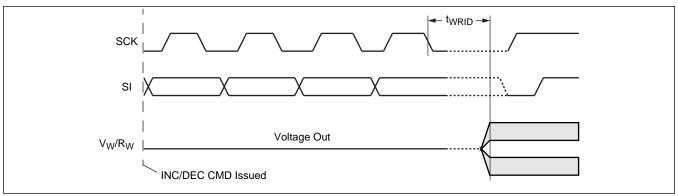


Table 1. Instruction Set

			Ir	stru	ction	Set			
Instruction	I ₃	I ₂	I ₁	I ₀	R ₁	R ₀	P ₁	P ₀	Operation
Read Wiper Counter Register	1	0	0	1	0	0	P ₁	P ₀	Read the contents of the Wiper Counter Register pointed to by P_1 - P_0
Write Wiper Counter Register	1	0	1	0	0	0	P ₁	P ₀	Write new value to the Wiper Counter Register pointed to by P_1 - P_0
Read Data Register	1	0	1	1	R ₁	R ₀	P ₁	P ₀	Read the contents of the Data Register pointed to by P_1 - P_0 and R_1 - R_0
Write Data Register	1	1	0	0	R ₁	R ₀	P ₁	P ₀	Write new value to the Data Register pointed to by P_1 - P_0 and R_1 - R_0
XFR Data Register to Wiper Counter Register	1	1	0	1	R ₁	R ₀	P ₁	P ₀	Transfer the contents of the Data Register pointed to by R_1-R_0 to the Wiper Counter Register pointed to by P_1-P_0
XFR Wiper Counter Register to Data Register	1	1	1	0	R ₁	R ₀	P ₁	P ₀	Transfer the contents of the Wiper Counter Register pointed to by P_1 - P_0 to the Register pointed to by R_1 - R_0
Global XFR Data Register to Wiper Counter Register	0	0	0	1	R ₁	R ₀	0	0	Transfer the contents of the Data Registers pointed to by R_1-R_0 of all four pots to their respective Wiper Counter Register
Global XFR Wiper Counter Register to Data Register	1	0	0	0	R ₁	R ₀	0	0	Transfer the contents of all Wiper Counter Registers to their respective data Registers pointed to by R_1-R_0 of all four pots
Increment/Decrement Wiper Counter Register	0	0	1	0	0	0	Р ₁	P ₀	Enable Increment/decrement of the Wiper Counter Register pointed to by P ₁ -P ₀
Read Status (WIP bit)	0	1	0	1	0	0	0	1	Read the status of the internal write cycle, by checking the WIP bit.

Instruction Format

Notes: (1) "A1 ~ A0": stands for the device addresses sent by the master.

- (2) WPx refers to wiper position data in the Counter Register
- (2) "I": stands for the increment operation, SI held HIGH during active SCK phase (high).
- (3) "D": stands for the decrement operation, SI held LOW during active SCK phase (high).

Read Wiper Counter Register(WCR)

CS			e ty tifie	•			/ice esse				uctic ode		a		CR esse	es	(:		-	er p X9))	CS
Falling Edge	0	1	0	1	0	0	A 1	A 0	1	0	0	1	0	0	P 1	P 0	W P 7	W P 6	W P 5	W P 4	W P 3	W P 2	W P 1	W P 0	Rising Edge

Write Wiper Counter Register (WCR)

CS			e ty tifie	•			vice esse			istru opc			a	W ddre	CR esse	es		(se		ata y H	-		SI)		CS
Falling Edge	0	1	0	1	0	0	A 1	A 0	1	0	1	0	0	0	P 1	P 0	W P 7	W P 6	W P 5	W P 4	W P 3	W P 2	W P 1	W P 0	Rising Edge

Read Data Register (DR)

CS			e ty tifie	•		dev ddre					uctic ode			ano ddre		-		sent			Byt 250		SC))	CS
Falling Edge	0	1	0	1	0	0	A 1	A 0	1	0	1	1	R 1	R 0	P 1	P 0	W P 7	W P 6	W P 5	W P 4	W P 3	W P 2	W P 1	W P 0	Rising Edge

Write Data Register (DR)

		vic		•		dev					ictic				d W			,		ata			0			
CS Falling		den	tifie	er	ac	ddre	esse	es	(opc	ode	;	a	ddre	esse	S		` 		by h W			, 	_	CS Rising	HIGH-VOLTAGE
Edge	0	1	0	1	0	0	A 1	A 0	1	1	0	0	R 1	R	P 1	P 0	P	Ρ	Ρ	Р	Ρ	P	P	P	Edge	WRITE CYCLE
													•				7	6	5	4	3	2	1	0		

Transfer Data Register (DR) to Wiper Counter Register (WCR)

CS Falling			e ty tifie	•		dev ddre					ictio ode				d W esse	-	CS Rising
Edge	0	1	0	1	0	0	A 1	A 0	1	1	0	1	R 1	R 0	P 1	P 0	Edge

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Transfer Wiper Counter Register (WCR) to Data Register (DR)

CS Falling			e ty tifie	•			/ice esse			stru opc					d W esse	CR s	CS Rising	HIGH-VOLTAGE
Edge	0	1	0	1	0	0	A 1	A 0	1	1	1	0	R 1	R 0	P 1	P 0	Edge	WRITE CYCLE

Increment/Decrement Wiper Counter Register (WCR)

CS Falling			e ty tifie	•	a	de\ ddre	/ice esse			stru opc			a	W0 ddre	-	es			-	 	-	nent n SI)		CS Rising
Edge	0	1	0	1	0	0	A 1	A 0	0	0	1	0	х	Х	Р 1	P 0	I/D	I/D				I/D	I/D	Edge

Global Transfer Data Register (DR) to Wiper Counter Register (WCR)

CS Falling			e ty tifie				/ice esse				ictic ode		a	D ddre	R esse	es	CS Rising
Edge	0	1	0	1	0	0	A 1	A 0	0	0	0	1	R 1	R 0	0	0	Edge

Global Transfer Wiper Counter Register (WCR) to Data Register (DR)

CS Falling			e ty tifie	•		dev ddre					uctio ode	-	ad	D ddre	R esse	es	CS Rising	HIGH-VOLTAGE
Edge	0	1	0	1	0	0	A 1	A 0	1	0	0	0	R 1	R 0	0	0	Edge	WRITE CYCLE

Read Status

CS			e ty tifie	•			/ice esse				uctic ode						(5	sent			By1 250		sc))	CS
Falling Edge	0	1	0	1	0	0	A 1	A 0	0	1	0	1	0	0	0	1	0	0	0	0	0	0	0	W I P	Rising Edge

ABSOLUTE MAXIMUM RATINGS

Temperature under bias65 to +135°C
Storage temperature–65 to +150°C
Voltage on SCK, SCL or any address input
with respect to V_{SS}
Voltage on V+ (referenced to V _{SS})10V
Voltage on V- (referenced to V _{SS})10V
(V+) – (V-)
Any V _H /R _H V+
Any V _L /R _L V-
Lead temperature (soldering, 10 seconds) 300°C
I _W (10 seconds)±15mA

COMMENT

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only; functional operation of the device (at these or any other conditions above those listed in the operational sections of this specification) is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Temperature	Min.	Max.		Device	Supply Voltage (V _{CC}) Limits
Commercial	O°C	+70°C		X9250	5V ±10%
Industrial	-40°C	+85°C	1	X9250-2.7	2.7V to 5.5V

POTENTIOMETER CHARACTERISTICS (Over recommended operating conditions unless otherwise stated.)

				Lin	nits		
Symbol	Paramet	ter	Min.	Тур.	Max.	Unit	Test Conditions
	End to end resistanc	e tolerance			±20	%	
	Power rating				50	mW	25°C, each pot
IW	Wiper current Wiper resistance				±7.5	mA	
R _W	Wiper resistance			150	250	Ω	Wiper current = ± 1 mA
Vv+	Voltage on V+ pin	X9250	+4.5		+5.5	V	
		X9250-2.7	+2.7		+5.5		
Vv-	Voltage on V- pin	X9250	-5.5		-4.5	V	
		X9250-2.7	-5.5		-2.7		
V _{TERM}	Voltage on any V _H /R	H or VL/RL pin	V-		V+	V	
	Noise			-120		dBV	Ref: 1kHz
	Resolution ⁽⁴⁾			0.6		%	
	Absolute linearity (1)				±1	MI ⁽³⁾	Vw(n)(actual)-Vw(n)(expected)
	Relative linearity (2)				±0.6	MI ⁽³⁾	$V_{w(n + 1)} - [V_{w(n) + MI}]$
	Temperature coefficient of R _{TOTAL}			±300		ppm/°C	
	Ratiometric Tempera Coefficient	ature			±20	ppm/°C	
C _H /C _L /C _W	Potentiometer Capac	citances		10/10/25		pF	See Circuit #3

Notes: (1) Absolute linearity is utilized to determine actual wiper voltage versus expected voltage as determined by wiper position when used as a potentiometer.

(2) Relative linearity is utilized to determine the actual change in voltage between two successive tap positions when used as a potentiometer. It is a measure of the error in step size.

(3) MI = RTOT/255 or $(V_H/R_H-V_L/R_L)/255$, single pot

(4) Individual array resolutions.

D.C. OPERATING CHARACTERISTICS (Over the recommended operating conditions unless otherwise specified.)

			Li	mits		
Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions
I _{CC1}	V _{CC} supply current (active)			400	μA	f _{SCK} = 2MHz, SO = Open, Other Inputs = V _{SS}
I _{CC2}	V _{CC} supply current (nonvolatile write)			1	mA	f _{SCK} = 2MHz, SO = Open, Other Inputs = V _{SS}
I _{SB}	V _{CC} current (standby)			5	μA	SCK = SI = V_{SS} , Addr. = V_{SS}
ILI	Input leakage current			10	μA	$V_{IN} = V_{SS}$ to V_{CC}
I _{LO}	Output leakage current			10	μA	$V_{OUT} = V_{SS}$ to V_{CC}
V _{IH}	Input HIGH voltage	V _{CC} x 0.7		V _{CC} + 0.1	V	
VIL	Input LOW voltage	-0.5		V _{CC} x 0.3	V	
V _{OL}	Output LOW voltage			0.4	V	I _{OL} = 3mA

ENDURANCE AND DATA RETENTION

Parameter	rameter Min. Unit		
Minimum endurance	100,000	Data changes per bit per register	
Data retention	100	Years	

CAPACITANCE

Symbol	Test	Max.	Unit	Test Conditions
C _{OUT} ⁽⁵⁾	Output capacitance (SO)	8	pF	V _{OUT} = 0V
C _{IN} ⁽⁵⁾	Input capacitance (A0, A1, SI, and SCK, CS)	6	pF	$V_{IN} = 0V$

POWER-UP TIMING

Symbol	Parameter	Min.	Max.	Unit
t _{PUR} ⁽⁶⁾	Power-up to initiation of read operation		1	ms
t _{PUW} ⁽⁶⁾	Power-up to initiation of write operation		5	ms
t _R V _{CC} ⁽⁷⁾	V _{CC} power up ramp rate	0.2	50	V/msec

POWER UP AND DOWN REQUIREMENT

The are no restrictions on the sequencing of the bias supplies V_{CC} , V+, and V- provided that all three supplies reach their final values within 1msec of each other. At all times, the voltages on the potentiometer pins must be less than V+ and more than V-. The recall of the wiper position from nonvolatile memory is not in effect until all supplies reach their final value. The V_{CC} ramp rate spec is always in effect.

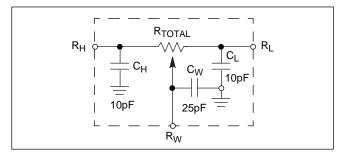
- Notes: (5) This parameter is periodically sampled and not 100% tested
 - (6) t_{PUR} and t_{PUW} are the delays required from the time the third (last) power supply (V_{CC}, V+ or V-) is stable until the specific instruction can be issued. These parameters are periodically sampled and not 100% tested.
 - (7) Sample tested only.

A.C. TEST CONDITIONS

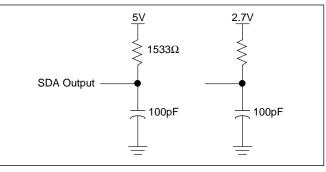
Input pulse levels	V_{CC} x 0.1 to V_{CC} x 0.9
Input rise and fall times	10ns
Input and output timing level	V _{CC} x 0.5

REV 1.1.5 1/31/03

Circuit #3 SPICE Macro Model



EQUIVALENT A.C. LOAD CIRCUIT



AC TIMING

Symbol	Parameter	Min.	Max.	Unit
f _{SCK}	SSI/SPI clock frequency		2.0	MHz
t _{CYC}	SSI/SPI clock cycle time	500		ns
t _{WH}	SSI/SPI clock high time	200		ns
t _{WL}	SSI/SPI clock low time	200		ns
t _{LEAD}	Lead time	250		ns
t _{LAG}	Lag time	250		ns
t _{SU}	SI, SCK, $\overline{\text{HOLD}}$ and $\overline{\text{CS}}$ input setup time	50		ns
t _H	SI, SCK, $\overline{\text{HOLD}}$ and $\overline{\text{CS}}$ input hold time	75		ns
t _{RI}	SI, SCK, $\overline{\text{HOLD}}$ and $\overline{\text{CS}}$ input rise time		2	μs
t _{FI}	SI, SCK, $\overline{\text{HOLD}}$ and $\overline{\text{CS}}$ input fall time		2	μs
t _{DIS}	SO output disable Time	0	500	ns
t _V	SO output valid time		100	ns
t _{HO}	SO output hold time	0		ns
t _{RO}	SO output rise time		50	ns
t _{FO}	SO output fall time		50	ns
t _{HOLD}	HOLD time	400		ns
t _{HSU}	HOLD setup time	100		ns
t _{HH}	HOLD hold time	100		ns
t _{HZ}	HOLD low to output in high Z		100	ns
t _{LZ}	HOLD high to output in low Z		100	ns
Τ _Ι	Noise suppression time constant at SI, SCK, \overline{HOLD} and \overline{CS} inputs		TBD	ns
t _{CS}	CS deselect time	2		μs
t _{WPASU}	WP, A0 and A1 setup time	0		ns
t _{WPAH}	WP, A0 and A1 hold time	0		ns

HIGH-VOLTAGE WRITE CYCLE TIMING

Symbol	Parameter	Тур.	Max.	Unit
t _{WR}	High-voltage write cycle time (store instructions)	5	10	ms

XDCP TIMING

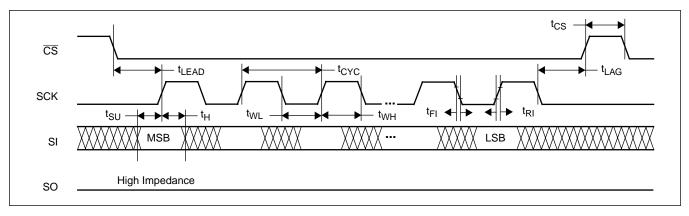
Symbol	Parameter	Min.	Max.	Unit
t _{WRPO}	Wiper response time after the third (last) power supply is stable		10	μs
t _{WRL}	Wiper response time after instruction issued (all load instructions)		10	μs
twrid	Wiper response time from an active SCL/SCK edge (increment/decrement instruc- tion)		40	μs

SYMBOL TABLE

WAVEFORM	INPUTS	OUTPUTS
	Must be steady	Will be steady
	May change from Low to High	Will change from Low to High
	May change from High to Low	Will change from High to Low
	Don't Care: Changes Allowed	Changing: State Not Known
	N/A	Center Line is High Impedance

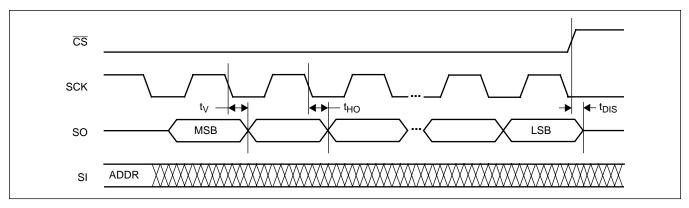
TIMING DIAGRAMS

Input Timing

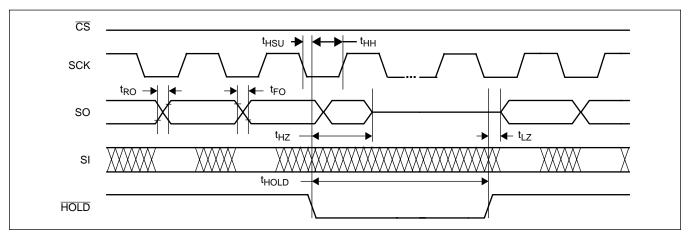


X9250

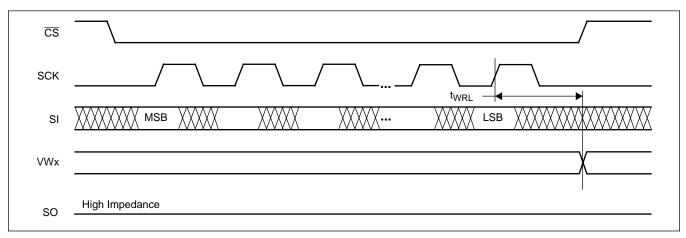
Output Timing



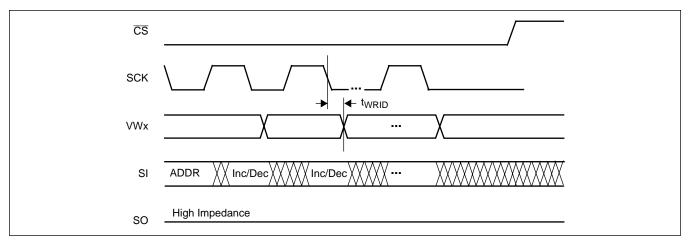
Hold Timing



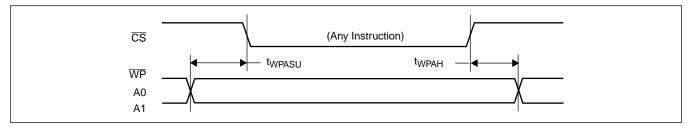
XDCP Timing (for all Load Instructions)



XDCP Timing (for Increment/Decrement Instruction)

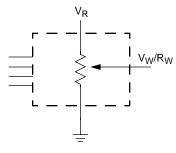


Write Protect and Device Address Pins Timing

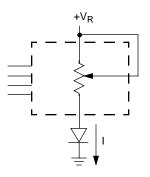


APPLICATIONS INFORMATION

Basic Configurations of Electronic Potentiometers



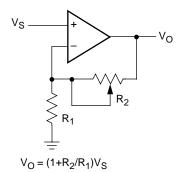
Three terminal Potentiometer; Variable voltage divider



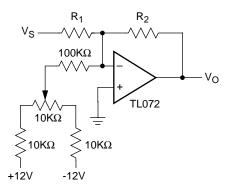
Two terminal Variable Resistor; Variable current

Application Circuits

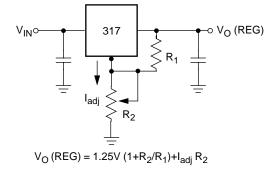
Noninverting Amplifier



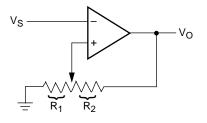




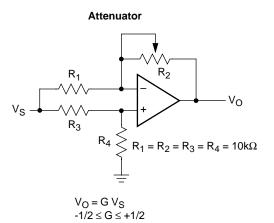
Voltage Regulator

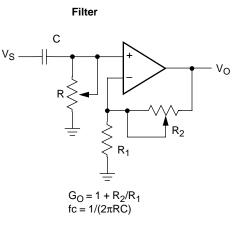


Comparator with Hysterisis

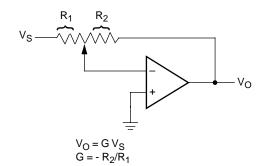


Application Circuits (continued)

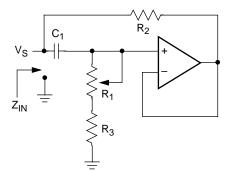


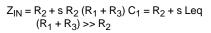


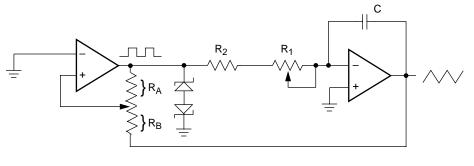










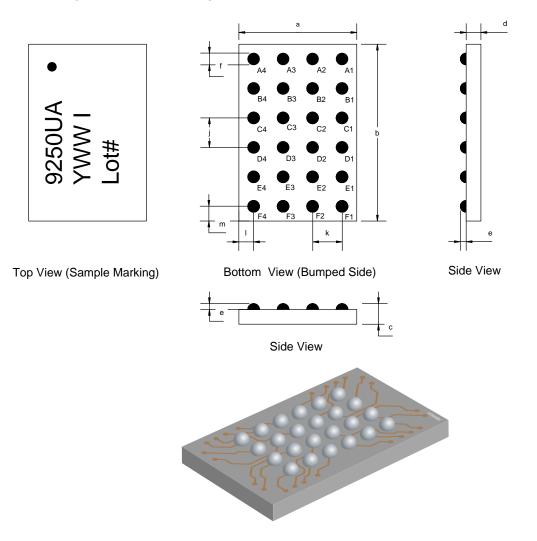


frequency $\propto R_1, R_2, C$ amplitude $\propto R_A, R_B$

X9250

PACKAGING INFORMATION

24-Bump Chip Scale Package (CSP B24) Package Outline Drawing



Package Dimensions

		Millimeters		
	Symbol	Min	Nominal	Max
Package Width	а	2.771	2.801	2.831
Package Length	b	4.549	4.579	4.609
Package Height	С	0.644	0.677	0.710
Body Thickness	d	0.444	0.457	0.470
Ball Height	е	0.200	0.220	0.240
Ball Diameter	f	0.300	0.320	0.340
Ball Pitch – Width	j		0.5	
Ball Pitch – Length	k		0.5	
Ball to Edge Spacing – Width	I	0.626	0.651	0.676
Ball to Edge Spacing – Length	m	1.015	1.040	1.065

Ball Matrix:

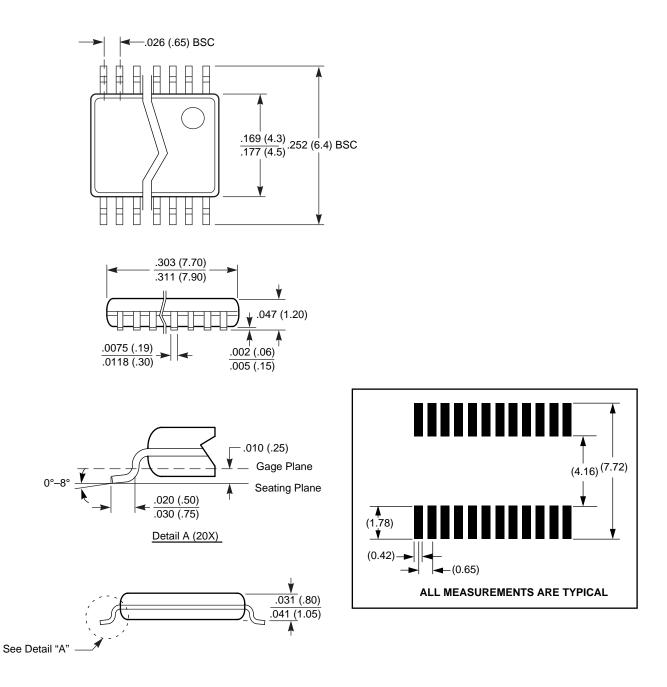
	4	3	2	1
Α	R _{L1}	A1	CS	R _{W0}
В	R _{W1}	SI	WP	R _{L0}
С	VSS	R _{H1}	R _{H0}	VCC
D	V-	RH2	R _{H3}	V+
E	R _{W2}	HOLD	SO	R _{L3}
F	R _{L2}	SCK	A0	R _{W3}

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PACKAGING INFORMATION

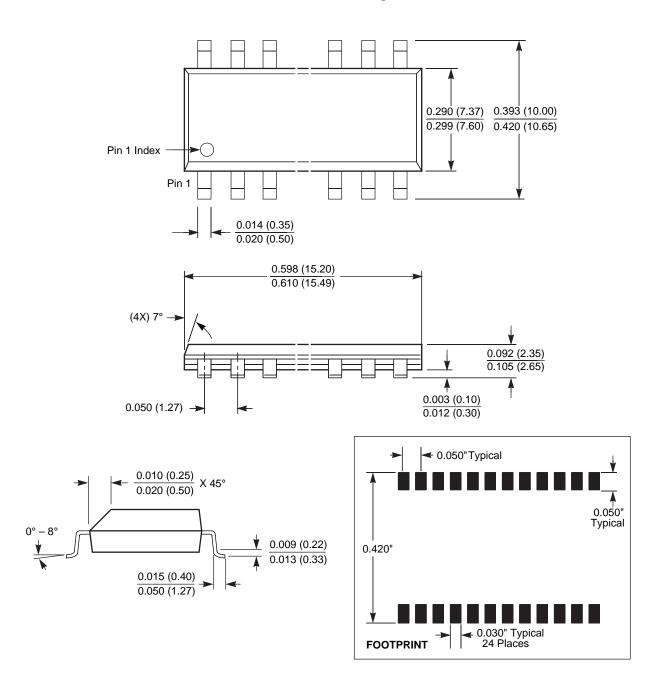




NOTE: ALL DIMENSIONS IN INCHES (IN PARENTHESES IN MILLIMETERS)

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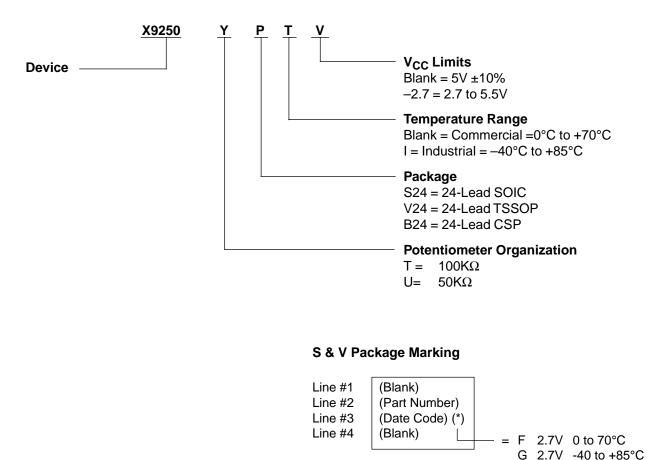
PACKAGING INFORMATION



24-Lead Plastic, SOIC, Package Code S24

NOTE: ALL DIMENSIONS IN INCHES (IN PARENTHESES IN MILLIMETERS)

Ordering Information



LIMITED WARRANTY

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